

WHAT IS CLAIMED IS:

1. A digital micro-mirror device (DMD) packages, comprising:
 - a base substrate having a top surface and a bottom surface;
 - 5 a metallic layer formed on the top surface of the base substrate;
 - a metallic adhesive formed on the metallic layer;
 - a semiconductor chip mounted on the metallic adhesive, the base substrate electrically connected with the semiconductor chip;
 - one or more mirrors mounted on the semiconductor chip;
- 10 a hermetic sealing means covering the semiconductor chip including the one more mirrors.

2. The DMD package of claim 1, which further comprises a heat sink attached on the bottom surface of the base substrate.

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